

SUBSTRATE FOR MOUNTING ELECTRONIC PARTS THEREON
AND METHOD OF MANUFACTURING SAME

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ABSTRACT OF THE DISCLOSURE

10 A substrate for mounting an electronic part or parts
thereon, which comprises a core substrate and at least a
set of insulation layer and patterned wiring line layer,
which is formed on the insulation layer, at at least one
side of the core substrate, the core substrate having
15 holes, in each of which a lead pin of the electronic part
to be mounted is to be inserted, and being provided with
lands which surround the opening of the hole and to which
the lead pin inserted in the hole is to be bonded,
wherein the insulation layer or layers at at least one
20 side of the core substrate has bores, which expose the
land at their bottoms, and communicate with the hole. A
method of manufacturing such a substrate is also
disclosed.